

**FEATURES**

- ±15-kV Human-Body Model (HBM) ESD Protection on Card Side
- Logic-Level Translation Between 1.8-V, 2.5-V, 3.3-V, and 5-V Supplies
- Integrated Card-Detect Circuitry
- Integrated Pullup/Pulldown Resistors Save Board Space and Cost
- Matched Pinout With CompactFlash™ (CF) Connector Pin Configurations to Optimize PCB Layout
- Input-Disable Feature Allows Floating Input Conditions
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Offered in 114-Ball LFBGA Package for Space-Constrained Applications
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Performance
  - ±15-kV HBM
  - ±4-kV IEC61000-4-2, Contact Discharge (Latch-Up Immune)

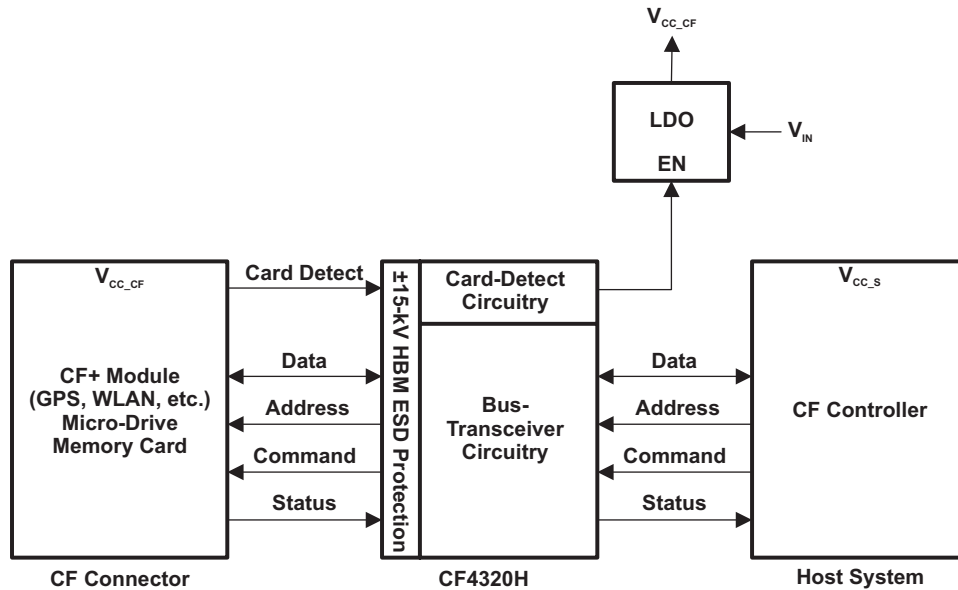
**TARGET APPLICATIONS**

- GPS PDAs
- PDA Phones
- Industrial PDAs
- High-End Digital Cameras

**DESCRIPTION/ORDERING INFORMATION**

The CF4320H is a CompactFlash™ (CF) interface device designed to provide a single-chip solution for CF card interfaces. Separate V<sub>CC</sub> rails for the system-bus side and the CF connector-bus side allow voltage-level shifting. This is helpful for interfacing between a core chipset that may operate from 3.3 V down to 1.65 V, and CF cards that operate from 3.3-V or 5-V supply voltages. All the input buffers feature the input-disable function, which allows conditional floating input signals. The input, output, and I/O buffers on the CF connector side have been defined to comply with CF+ and CF specification revisions 1.4 and 2.0.

**TYPICAL APPLICATION**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

CompactFlash is a trademark of Sandisk Corporation.

## CARD-DETECT CIRCUIT

The CF4320H has an integrated card-detect circuit that generates a LOW card-detect signal when a CF card is plugged into the socket. This circuit is supplied by a separate power-supply pin,  $V_{CC\_SD}$ , which operates from 1.65 V to 5.5 V. The card-detect signal can be used to control a voltage regulator, which may power the CF slot and the CF side of the CF4320H. The inputs to this circuitry ( $\overline{CD1}$  and  $\overline{CD2}$ ) have internal pullup resistors to pull them to a HIGH logic state if there is no card in the CF slot.  $V_{CC\_SD}$  is particularly helpful when the core processor operates at a low  $V_{CC}$ , but the regulator needs a higher control-signal voltage.

### CARD-DETECT SIGNALS

INPUTS		OUTPUT $\overline{SCD}$
$\overline{CD1}$	$\overline{CD2}$	
L	L	L
L	H	H
H	L	H
H	H	H

### ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	LFBGA – GKF	Tape and reel	CF4320HGKFR	CF4320
	LFBGA – ZKF	Tape and reel	CF4320HZKFR	CF4320

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## BUS-TRANSCEIVER CIRCUIT

### Command and Status Bits

Most CF controllers are embedded in processors or microcontrollers and use GPIOs to send command signals and receive status signals from the card to manage operation. The CF interface consists of eight control signals and six status signals. The CF standard requires that each of these signals have a 100-k $\Omega$  pullup resistor. The CF4320H includes an internal 100-k $\Omega$  pullup resistor on the input of each of these signals, which saves board real estate and lowers overall system cost

### COMMAND LINE BUFFERS<sup>(1)</sup> ( $\overline{BVD1}$ , $\overline{BVD2}$ , $\overline{INPACK}$ , $\overline{OE}$ , $\overline{IORD}$ , $\overline{IOWR}$ , $\overline{READY}$ , $\overline{REG}$ , $\overline{CE1}$ , $\overline{CE2}$ , $\overline{WAIT}$ , $\overline{WE}$ , $\overline{WP}$ )

INPUTS			OUTPUT
$\overline{MASTER\_EN}$	$\overline{BUF\_EN}$	INPUT	
L	L	H	H
L	L	L	L
L	H	X	Z, Command line buffer inputs can float.
H	X	X	Z, low-power mode

(1) X = H or L

### RESET<sup>(1)</sup>

INPUTS		OUTPUT RESET
$\overline{MASTER\_EN}$	$\overline{SRESET}$	
L	H	H
L	L	L
H	X	Z, low-power mode

(1) X = H or L

### Data Bits

The CF4320H has 16 data lines organized as two groups of 8 bits each. The  $\overline{\text{ENL}}$  signal controls the lower 8 bits (D07–D00), while the  $\overline{\text{ENH}}$  signal controls the upper 8 bits (D15–D08).

#### LOWER 8-BIT DATA BUS TRANSCEIVERS<sup>(1)</sup> (D07–D00, SD07–SD00)

INPUTS			OPERATION
$\overline{\text{MASTER\_EN}}$	$\overline{\text{ENL}}$	DIR ( $\overline{\text{S}}/\text{CF}$ )	
L	L	H	SD data to D bus
L	L	L	D data to SD bus
L	H	X	Isolation. D07–D00 and SD07–SD00 inputs can float.
H	X	X	Isolation, low-power mode

(1) X = H or L

#### UPPER 8-BIT DATA BUS TRANSCEIVERS<sup>(1)</sup> (D15–D08, SD15–SD08)

INPUTS			OPERATION
$\overline{\text{MASTER\_EN}}$	$\overline{\text{ENH}}$	DIR ( $\overline{\text{S}}/\text{CF}$ )	
L	L	H	SD data to D bus
L	L	L	D data to SD bus
L	H	X	Isolation. D15–D08 and SD15–SD08 inputs can float.
H	X	X	Isolation, low-power mode

(1) X = H or L

### Address Bits

The CF4320H has 11 unidirectional address bits flowing from the system to the CF card.

#### ADDRESS BUS BUFFERS<sup>(1)</sup>

INPUTS			OUTPUT A
$\overline{\text{MASTER\_EN}}$	$\overline{\text{BUF\_EN}}$	SA	
L	L	H	H
L	L	L	L
L	H	X	Z, SA inputs can float.
H	X	X	Z, low-power mode

(1) X = H or L

### Direction Signal Bit

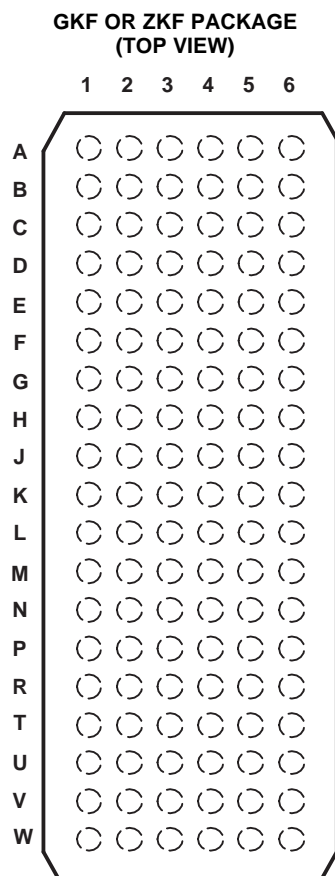
The DIR( $\overline{S}/CF$ ) input controls the data direction between the system bus and the CF card. The CF4320H has circuitry to generate a DIR\_OUT signal using the  $\overline{SOE}$  and  $\overline{SIORD}$  signals. DIR( $\overline{S}/CF$ ) and DIR\_OUT are placed adjacent to each other, which is convenient for connecting DIR( $\overline{S}/CF$ ) and DIR\_OUT, if DIR\_OUT is used. This saves an additional signal from the system controller to control the data direction. When either  $\overline{SOE}$  or  $\overline{SIORD}$  is low, the data direction is from the CF card side to the system side (DIR\_OUT = L).

DIR\_OUT<sup>(1)</sup>

INPUTS				OUTPUT DIR_OUT
BUF_EN	MASTER_EN	SOE	SIORD	
L	L	L	L	L
L	L	L	H	L
L	L	H	L	L
L	L	H	H	H
H	L	X	X	L
X	H	X	X	Z, low-power mode

(1) X = H or L

### BOARD-OPTIMIZED PIN CONFIGURATION



### TERMINAL ASSIGNMENTS

	1	2	3	4	5	6
<b>A</b>	D12	D04	D03	SD14	SD12	SD11
<b>B</b>	D13	D05	D11	SD13	SD10	SD09
<b>C</b>	D14	D06	SD15	SINPACK	SD08	SD07
<b>D</b>	D15	D07	V <sub>CC_C</sub> F	V <sub>CC_S</sub>	SD06	SD05
<b>E</b>	$\overline{CE2}$	$\overline{CE1}$	GND	GND	SD04	SD03
<b>F</b>	$\overline{OE}$	A10	V <sub>CC_C</sub> F	V <sub>CC_S</sub>	SD02	SD01
<b>G</b>	A09	$\overline{IORD}$	GND	GND	SD00	$\overline{SCE1}$
<b>H</b>	A08	$\overline{IOWR}$	V <sub>CC_C</sub> F	V <sub>CC_S</sub>	ENL	ENH
<b>J</b>	A07	$\overline{WE}$	GND	GND	MASTER_EN	BUF_EN
<b>K</b>	A06	READY	A05	$\overline{SCE2}$	$\overline{SOE}$	$\overline{SIORD}$
<b>L</b>	A04	RESET	GND	GND	$\overline{SWE}$	$\overline{SIOWR}$
<b>M</b>	A03	$\overline{WAIT}$	V <sub>CC_C</sub> F	V <sub>CC_S</sub>	SREADY	SRESET
<b>N</b>	A02	INPACK	GND	GND	$\overline{SWAIT}$	$\overline{SREG}$
<b>P</b>	A01	$\overline{REG}$	V <sub>CC_C</sub> F	GND	SBVD2	SBVD1
<b>R</b>	A00	BVD2	V <sub>CC_C</sub> F	V <sub>CC_S</sub>	SA10	SWP
<b>T</b>	D00	BVD1	V <sub>CC_SD</sub>	DIR( $\overline{S}$ /CF)	SA08	SA09
<b>U</b>	D01	D08	$\overline{CD1}$	DIR_OUT	SA06	SA07
<b>V</b>	D02	D09	$\overline{CD2}$	SA00	SA04	SA05
<b>W</b>	WP	D10	$\overline{SCD}$	SA01	SA02	SA03

## TERMINAL FUNCTIONS

TERMINAL		DESCRIPTION	REFERENCED TO	I/O <sup>(1)</sup>
NO.	NAME			
A1	D12	Data bit 12 connected to card	V <sub>CC_Cf</sub>	I/O
B1	D13	Data bit 13 connected to card	V <sub>CC_Cf</sub>	I/O
C1	D14	Data bit 14 connected to card	V <sub>CC_Cf</sub>	I/O
D1	D15	Data bit 15 connected to card	V <sub>CC_Cf</sub>	I/O
E1	$\overline{CE2}$	Card enable connected to card	V <sub>CC_Cf</sub>	O
F1	$\overline{OE}$	Output enable connected to card	V <sub>CC_Cf</sub>	O
G1	A09	Address bit 9 connected to card	V <sub>CC_Cf</sub>	O
H1	A08	Address bit 8 connected to card	V <sub>CC_Cf</sub>	O
J1	A07	Address bit 7 connected to card	V <sub>CC_Cf</sub>	O
K1	A06	Address bit 6 connected to card	V <sub>CC_Cf</sub>	O
L1	A04	Address bit 4 connected to card	V <sub>CC_Cf</sub>	O
M1	A03	Address bit 3 connected to card	V <sub>CC_Cf</sub>	O
N1	A02	Address bit 2 connected to card	V <sub>CC_Cf</sub>	O
P1	A01	Address bit 1 connected to card	V <sub>CC_Cf</sub>	O
R1	A00	Address bit 0 connected to card	V <sub>CC_Cf</sub>	O
T1	D00	Data bit 0 connected to card	V <sub>CC_Cf</sub>	I/O
U1	D01	Data bit 1 connected to card	V <sub>CC_Cf</sub>	I/O
V1	D02	Data bit 2 connected to card	V <sub>CC_Cf</sub>	I/O
W1	WP	Write protect connected to card. Pulled up to V <sub>CC_Cf</sub> through 100 kΩ.	V <sub>CC_Cf</sub>	I
A2	D04	Data bit 4 connected to card	V <sub>CC_Cf</sub>	I/O
B2	D05	Data bit 5 connected to card	V <sub>CC_Cf</sub>	I/O
C2	D06	Data bit 6 connected to card	V <sub>CC_Cf</sub>	I/O
D2	D07	Data bit 7 connected to card	V <sub>CC_Cf</sub>	I/O
E2	$\overline{CE1}$	Card enable connected to card	V <sub>CC_Cf</sub>	O
F2	A10	Address bit 10 connected to card	V <sub>CC_Cf</sub>	O
G2	$\overline{IORD}$	I/O read connected to card	V <sub>CC_Cf</sub>	O
H2	$\overline{IOWR}$	I/O write connected to card	V <sub>CC_Cf</sub>	O
J2	$\overline{WE}$	Write enable connected to card	V <sub>CC_Cf</sub>	O
K2	READY	Ready connected to card. Pulled up to V <sub>CC_Cf</sub> through 100 kΩ.	V <sub>CC_Cf</sub>	I
L2	RESET	Reset connected to card	V <sub>CC_Cf</sub>	O
M2	$\overline{WAIT}$	Wait connected to card. Pulled up to V <sub>CC_Cf</sub> through 100 kΩ.	V <sub>CC_Cf</sub>	I
N2	$\overline{INPACK}$	Input acknowledge connected to card. Pulled up to V <sub>CC_Cf</sub> through 100 kΩ.	V <sub>CC_Cf</sub>	I
P2	$\overline{REG}$	Register connected to card	V <sub>CC_Cf</sub>	O
R2	BVD2	BVD2 connected to card. Pulled up to V <sub>CC_Cf</sub> through 100 kΩ.	V <sub>CC_Cf</sub>	I
T2	BVD1	BVD1 connected to card. Pulled up to V <sub>CC_Cf</sub> through 100 kΩ.	V <sub>CC_Cf</sub>	I
U2	D08	Data bit 8 connected to card	V <sub>CC_Cf</sub>	I/O
V2	D09	Data bit 9 connected to card	V <sub>CC_Cf</sub>	I/O
W2	D10	Data bit 10 connected to card	V <sub>CC_Cf</sub>	I/O
A3	D03	Data bit 3 connected to card	V <sub>CC_Cf</sub>	I/O
B3	D11	Data bit 11 connected to card	V <sub>CC_Cf</sub>	I/O
C3	SD15	Data bit 15 connected to controller	V <sub>CC_S</sub>	I/O
D3	V <sub>CC_Cf</sub>	Card-side supply voltage. V <sub>CC_Cf</sub> powers all card-side inputs, outputs, and I/Os.		Power
E3	GND	Ground		
F3	V <sub>CC_Cf</sub>	Card-side supply voltage. V <sub>CC_Cf</sub> powers all card-side inputs, outputs, and I/Os.		Power
G3	GND	Ground		

(1) I = input, O = output, I/O = input/output

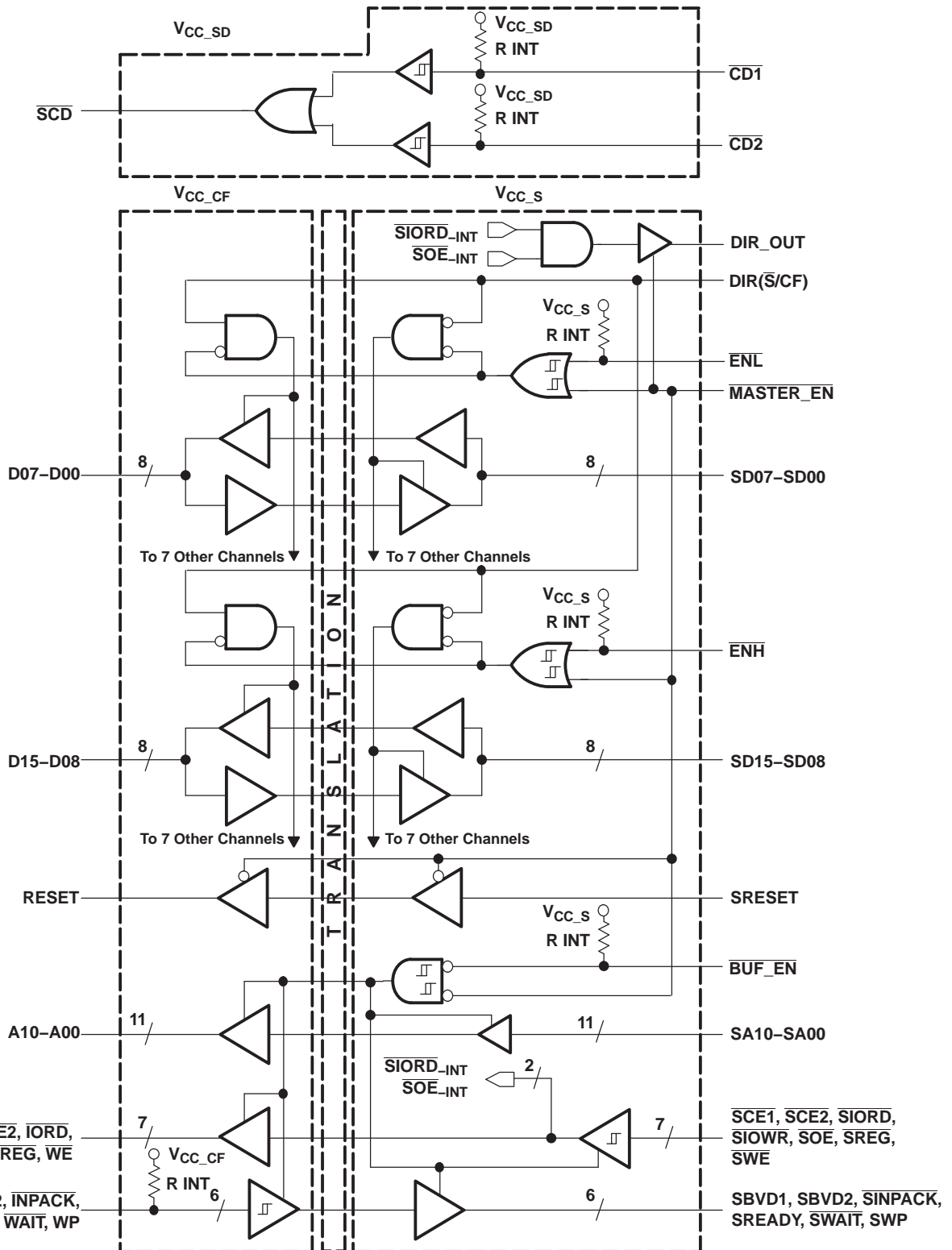
### TERMINAL FUNCTIONS (continued)

TERMINAL		DESCRIPTION	REFERENCED TO	I/O <sup>(1)</sup>
NO.	NAME			
H3	V <sub>CC_CF</sub>	Card-side supply voltage. V <sub>CC_CF</sub> powers all card-side inputs, outputs, and I/Os.		Power
J3	GND	Ground		
K3	A05	Address bit 5 connected to card	V <sub>CC_CF</sub>	O
L3	GND	Ground		
M3	V <sub>CC_CF</sub>	Card-side supply voltage. V <sub>CC_CF</sub> powers all card-side inputs, outputs, and I/Os.		Power
N3	GND	Ground		
P3	V <sub>CC_CF</sub>	Card-side supply voltage. V <sub>CC_CF</sub> powers all card-side inputs, outputs, and I/Os.		Power
R3	V <sub>CC_CF</sub>	Card-side supply voltage. V <sub>CC_CF</sub> powers all card-side inputs, outputs, and I/Os.		Power
T3	V <sub>CC_SD</sub>	Card-detect supply voltage. V <sub>CC_SD</sub> powers the card-detect circuitry.		Power
U3	$\overline{CD1}$	Card detect connected to card. Pulled up to V <sub>CC_CF</sub> through 100 k $\Omega$ .	V <sub>CC_SD</sub>	I
V3	$\overline{CD2}$	Card detect connected to card. Pulled up to V <sub>CC_CF</sub> through 100 k $\Omega$ .	V <sub>CC_SD</sub>	I
W3	$\overline{SCD}$	Card detect connected to controller	V <sub>CC_SD</sub>	O
A4	SD14	Data bit 14 connected to controller	V <sub>CC_s</sub>	I/O
B4	SD13	Data bit 13 connected to controller	V <sub>CC_s</sub>	I/O
C4	$\overline{SINPACK}$	Input acknowledge connected to controller	V <sub>CC_s</sub>	I/O
D4	V <sub>CC_s</sub>	Controller-side supply voltage. V <sub>CC_s</sub> powers all controller-side inputs, outputs, and I/Os.		Power
E4	GND	Ground		
F4	V <sub>CC_s</sub>	Controller-side supply voltage. V <sub>CC_s</sub> powers all controller-side inputs, outputs, and I/Os.		Power
G4	GND	Ground		
H4	V <sub>CC_s</sub>	Controller-side supply voltage. V <sub>CC_s</sub> powers all controller-side inputs, outputs, and I/Os.		Power
J4	GND	Ground		
K4	$\overline{SCE2}$	Card enable connected to controller	V <sub>CC_s</sub>	I
L4	GND	Ground		
M4	V <sub>CC_s</sub>	Controller-side supply voltage. V <sub>CC_s</sub> powers all controller-side inputs, outputs, and I/Os.		Power
N4	GND	Ground		
P4	GND	Ground		
R4	V <sub>CC_s</sub>	Controller-side supply voltage. V <sub>CC_s</sub> powers all controller-side inputs, outputs, and I/Os.		Power
T4	DIR( $\overline{S}/CF$ )	Direction controls flow of data from system to CF and vice-versa	V <sub>CC_s</sub>	I
U4	DIR_OUT	Data direction generated by CF4320H. Can be connected to DIR( $\overline{S}/CF$ ).	V <sub>CC_s</sub>	O
V4	SAO0	Address bit 0 connected to controller	V <sub>CC_s</sub>	I
W4	SAO1	Address bit 1 connected to controller	V <sub>CC_s</sub>	I
A5	SD12	Data bit 12 connected to controller	V <sub>CC_s</sub>	I/O
B5	SD10	Data bit 10 connected to controller	V <sub>CC_s</sub>	I/O
C5	SD08	Data bit 8 connected to controller	V <sub>CC_s</sub>	I/O
D5	SD06	Data bit 6 connected to controller	V <sub>CC_s</sub>	I/O
E5	SD04	Data bit 4 connected to controller	V <sub>CC_s</sub>	I/O
F5	SD02	Data bit 2 connected to controller	V <sub>CC_s</sub>	I/O
G5	SD00	Data bit 0 connected to controller	V <sub>CC_s</sub>	I/O
H5	$\overline{ENL}$	Enable for data bits 0–7. Pulled up to V <sub>CC_s</sub> through 100 k $\Omega$ .	V <sub>CC_s</sub>	I
J5	$\overline{MASTER\_EN}$	Enable for all transceivers and buffers except the card-detect circuitry	V <sub>CC_s</sub>	I
K5	$\overline{SOE}$	Output enable connected to controller	V <sub>CC_s</sub>	I
L5	$\overline{SWE}$	Write enable connected to controller	V <sub>CC_s</sub>	I
M5	SREADY	Ready connected to controller	V <sub>CC_s</sub>	O

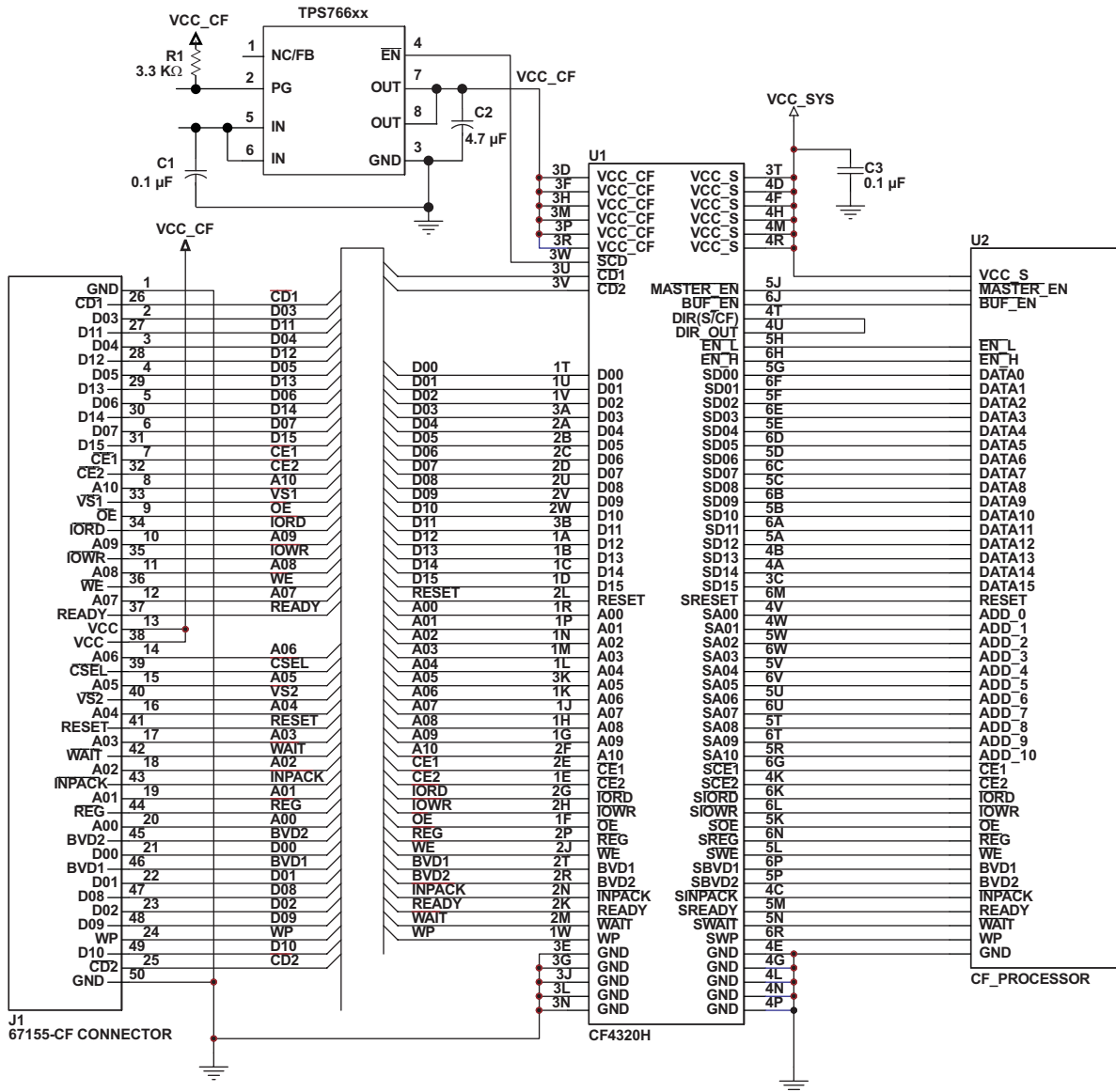
## TERMINAL FUNCTIONS (continued)

TERMINAL		DESCRIPTION	REFERENCED TO	I/O <sup>(1)</sup>
NO.	NAME			
N5	$\overline{\text{SWAIT}}$	Wait connected to controller	V <sub>CC_S</sub>	O
P5	SBVD2	BVD2 connected to controller	V <sub>CC_S</sub>	O
R5	SA10	Address bit 10 connected to controller	V <sub>CC_S</sub>	I
T5	SA08	Address bit 8 connected to controller	V <sub>CC_S</sub>	I
U5	SA06	Address bit 6 connected to controller	V <sub>CC_S</sub>	I
V5	SA04	Address bit 4 connected to controller	V <sub>CC_S</sub>	I
W5	SA02	Address bit 2 connected to controller	V <sub>CC_S</sub>	I
A6	SD11	Data bit 11 connected to controller	V <sub>CC_S</sub>	I/O
B6	SD09	Data bit 9 connected to controller	V <sub>CC_S</sub>	I/O
C6	SD07	Data bit 7 connected to controller	V <sub>CC_S</sub>	I/O
D6	SD05	Data bit 5 connected to controller	V <sub>CC_S</sub>	I/O
E6	SD03	Data bit 3 connected to controller	V <sub>CC_S</sub>	I/O
F6	SD01	Data bit 1 connected to controller	V <sub>CC_S</sub>	I/O
G6	$\overline{\text{SCE1}}$	Card enable connected to controller	V <sub>CC_S</sub>	I
H6	$\overline{\text{ENH}}$	Enable for data bits 8–15. Pulled up to V <sub>CC_S</sub> through 100 kΩ.	V <sub>CC_S</sub>	I
J6	$\overline{\text{BUF\_EN}}$	Enable for address and control/status lines. Pulled up to V <sub>CC_S</sub> through 100 kΩ.	V <sub>CC_S</sub>	I
K6	$\overline{\text{SIORD}}$	I/O read connected to controller	V <sub>CC_S</sub>	I
L6	$\overline{\text{SIOWR}}$	I/O write connected to controller	V <sub>CC_S</sub>	I
M6	SRESET	Reset connected to controller	V <sub>CC_S</sub>	I
N6	$\overline{\text{SREG}}$	Register connected to controller	V <sub>CC_S</sub>	I
P6	SBVD1	BVD1 connected to controller	V <sub>CC_S</sub>	O
R6	SWP	Write protect connected to controller	V <sub>CC_S</sub>	O
T6	SA09	Address bit 9 connected to controller	V <sub>CC_S</sub>	I
U6	SA07	Address bit 7 connected to controller	V <sub>CC_S</sub>	I
V6	SA05	Address bit 5 connected to controller	V <sub>CC_S</sub>	I
W6	SA03	Address bit 3 connected to controller	V <sub>CC_S</sub>	I

LOGIC DIAGRAM



NOTE: R INT ≥ 100 kΩ



### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
$V_{CC\_S}$	Supply voltage range		-0.5	4.6	V	
$V_{CC\_CF}$			-0.5	6.5		
$V_{CC\_SD}$						
$V_I$	Input voltage range	I/O ports	SD, SA <sup>(2)</sup>	-0.5	4.6	V
			D, A	-0.5	6.5	
		Input ports	SCE1, SCE2, SIORD, SIOWR, SOE, SREG, SWE	-0.5	4.6	
			BVD1, BVD2, READY, INPACK, WAIT, WP	-0.5	6.5	
Control ports	DIR( $\bar{S}/CF$ ), MASTER_EN, ENL, ENH	-0.5	4.6			
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	System port	-0.5	4.6	V	
		CF port	-0.5	6.5		
$V_O$	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	System port	-0.5	$V_{CC\_S} + 0.5$	V	
		CF port	-0.5	$V_{CC\_CF} + 0.5$		
$I_{IK}$	Input clamp current	$V_I < 0$		-50	mA	
$I_{OK}$	Output clamp current	$V_O < 0$		-50	mA	
$I_O$	Continuous output current			±50	mA	
	Continuous current through each $V_{CC\_S}$ , $V_{CC\_CF}$ , $V_{CC\_SD}$ , or GND			±100	mA	
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>			36	°C/W	
$T_{stg}$	Storage temperature range			-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 6.5 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions<sup>(1)(2)(3)</sup>

			V <sub>CCI</sub>	V <sub>CCO</sub>	MIN	MAX	UNIT
V <sub>CC_SD</sub>	Card-detect supply voltage				1.65	5.5	V
V <sub>CC_S</sub>	System-side supply voltage				1.65	V <sub>CC_CF</sub>	V
V <sub>CC_CF</sub>	CF-side supply voltage				3	5.5	V
V <sub>IH</sub>	High-level input voltage	Card-detect inputs (CD1, CD2)	1.65 V to 5.5 V		V <sub>CC_SD</sub> × 0.65		V
V <sub>IL</sub>	Low-level input voltage	Card-detect inputs (CD1, CD2)	1.65 V to 5.5 V		V <sub>CC_SD</sub> × 0.35		V
V <sub>IH</sub>	High-level input voltage	System port (SD, SA, SRESET)	1.65 V to 1.95 V		V <sub>CC_S</sub> × 0.65		V
			1.95 V to 2.7 V		1.7		
			2.7 V to 3.6 V		2		
V <sub>IL</sub>	Low-level input voltage	System port (SD, SA, SRESET)	1.65 V to 1.95 V		V <sub>CC_S</sub> × 0.35		V
			1.95 V to 2.7 V		0.7		
			2.7 V to 3.6 V		0.8		
V <sub>IH</sub>	High-level input voltage	Control inputs (DIR, MASTER_EN, ENL, ENH, BUF_EN)	1.65 V to 1.95 V		V <sub>CC_S</sub> × 0.65		V
			1.95 V to 2.7 V		1.7		
			2.7 V to 3.6 V		2		
V <sub>IL</sub>	Low-level input voltage	Control inputs (DIR, MASTER_EN, ENL, ENH, BUF_EN)	1.65 V to 1.95 V		V <sub>CC_S</sub> × 0.35		V
			1.95 V to 2.7 V		0.7		
			2.7 V to 3.6 V		0.8		
V <sub>IH</sub>	High-level input voltage	CF port (D, A)	3 V to 3.6 V		2		V
			4.5 V to 5.5 V		V <sub>CC_CF</sub> × 0.7		
V <sub>IL</sub>	Low-level input voltage	CF port (D, A)	3 V to 3.6 V		0.8		V
			4.5 V to 5.5 V		V <sub>CC_CF</sub> × 0.3		
V <sub>O</sub>	Card-detect output voltage				0	V <sub>CC_SD</sub>	V
	System-side output voltage				0	V <sub>CC_S</sub>	
	CF-side output voltage				0	V <sub>CC_CF</sub>	
I <sub>OH</sub>	High-level output current	Card detect	1.65 V to 1.95 V		–2		mA
			1.95 V to 2.7 V		–4		
			2.7 V to 3.6 V		–8		
			4.5 V to 5.5 V		–12		
I <sub>OL</sub>	Low-level output current	Card detect	1.65 V to 1.95 V		2		mA
			1.95 V to 2.7 V		4		
			2.7 V to 3.6 V		8		
			4.5 V to 5.5 V		12		
I <sub>OH</sub>	High-level output current	System port	1.65 V to 1.95 V		2		mA
			1.95 V to 2.7 V		6		
			2.7 V to 3.6 V		12		
I <sub>OL</sub>	Low-level output current	System port	1.65 V to 1.95 V		2		mA
			1.95 V to 2.7 V		6		
			2.7 V to 3.6 V		12		
I <sub>OH</sub>	High-level output current	CF port	3 V to 3.6 V		12		mA
			4.5 V to 5.5 V		16		
I <sub>OL</sub>	Low-level output current	CF port	3 V to 3.6 V		12		mA
			4.5 V to 5.5 V		16		

(1) V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.(2) V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.(3) All unused data inputs of the device must be held at V<sub>CCI</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

### Recommended Operating Conditions (continued)

		V <sub>CCI</sub>	V <sub>CCO</sub>	MIN	MAX	UNIT
$\Delta t/\Delta v$	Input transition rise or fall rate	1.65 V to 2.7 V			>20	ns/V
		2.7 V to 3.6 V		>20		
		4.5 V to 5.5 V		>20		
T <sub>A</sub>	Operating free-air temperature			–40	85	°C

### Electrical Characteristics

over recommended operating free-air temperature range (CF card-detect logic) (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC_SD</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub>	I <sub>OH</sub> = –100 μA	1.65 V to 5.5 V	V <sub>CC_SD</sub> – 0.1		V <sub>CC_SD</sub> – 0.2	V	
		I <sub>OH</sub> = –2 mA	1.65 V	1.2		1.2		
		I <sub>OH</sub> = –4 mA	2.3 V	2		2		
		I <sub>OH</sub> = –6 mA	2.7 V	2.3		2.3		
		I <sub>OH</sub> = –8 mA	3 V	2.4		2.4		
		I <sub>OH</sub> = –12 mA	4.5 V	3.8		3.8		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 5.5 V		0.1	0.2	V	
		I <sub>OL</sub> = 2 mA	1.65 V		0.2	0.2		
		I <sub>OL</sub> = 4 mA	2.3 V		0.2	0.2		
		I <sub>OL</sub> = 6 mA	2.7 V		0.3	0.3		
		I <sub>OL</sub> = 8 mA	3 V		0.4	0.4		
		I <sub>OL</sub> = 12 mA	4.5 V		0.5	0.5		
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC_SD</sub>	1.65 V to 5.5 V		±0.5	±1	μA		
	V <sub>I</sub> = 0 V			–55	–60			
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V	0 V		55	60	μA		
R <sub>INT</sub>	$\overline{CD1}$ = GND, $\overline{CD2}$ = GND	1.65 V to 5.5 V	150	300	100	300	kΩ	
I <sub>CC_SD</sub>	$\overline{CD1}$ and $\overline{CD2}$ = V <sub>CC_SD</sub> , I <sub>O_SD</sub> = 0	5.5 V		0.5	1	μA		
	$\overline{CD1}$ or $\overline{CD2}$ = GND, $\overline{CD2}$ or $\overline{CD1}$ = V <sub>CC_SD</sub> , I <sub>O_SD</sub> = 0			10	10			
C <sub>1</sub>	$\overline{CD1}$ or $\overline{CD2}$	V <sub>I</sub> = V <sub>CC_SD</sub> or GND	5.5 V	9			pF	

**Electrical Characteristics**<sup>(1)(2)</sup>

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V <sub>CC_S</sub>	V <sub>CC_CF</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		UNIT
						MIN	TYP	MAX	MIN	MAX	
V <sub>T+</sub>	SOE, SCE1, SCE2, SIORD, SIOWR, SWE, SREG			1.65 V	3 V to 5.5 V	0.95			0.6	1.4	V
				2.3 V		1.32			0.9	1.8	
				2.7 V		1.49			1	2	
				3 V		1.67			1.2	2.2	
V <sub>T–</sub>	SOE, SCE1, SCE2, SIORD, SIOWR, SWE, SREG			1.65 V	3 V to 5.5 V	0.66			0.19	0.8	V
				2.3 V		0.87			0.39	1.15	
				2.7 V		0.98			0.49	1.32	
				3 V		1.08			0.59	1.5	
ΔV <sub>T</sub>	SOE, SCE1, SCE2, SIORD, SIOWR, SWE, SREG			1.65 V	3 V to 5.5 V	0.31			0.1	0.7	V
				2.3 V		0.46			0.25	0.7	
				2.7 V		0.52			0.3	0.9	
				3 V		0.61			0.4	0.9	
V <sub>T+</sub>	BVD1, BVD2, READY, INPACK, WAIT			1.65 V to 3.6 V	3 V	1.67			1.3	2.2	V
					4.5 V	2.44			1.9	3.1	
V <sub>T–</sub>	BVD1, BVD2, READY, INPACK, WAIT, WP			1.65 V to 3.6 V	3 V	1.11			0.6	1.5	V
					4.5 V	1.43			1	2	
ΔV <sub>T</sub>	BVD1, BVD2, READY, INPACK, WAIT			1.65 V to 3.6 V	3 V	0.58			0.35	1	V
					4.5 V	1.02			0.6	1.5	
V <sub>T+</sub>	BUF_EN, ENH, ENL, MASTER_EN			1.65 V	3 V to 5.5 V	1			0.6	1.4	V
				2.3 V		1.37			1.1	1.8	
				2.7 V		1.54			1.1	2	
				3 V		1.72			1.3	2.2	
V <sub>T–</sub>	BUF_EN, ENH, ENL, MASTER_EN			1.65 V	3 V to 5.5 V	0.34			0.15	1	V
				2.3 V		0.63			0.15	1.2	
				2.7 V		0.75			0.2	1.32	
				3 V		0.88			0.4	1.5	
ΔV <sub>T</sub>	BUF_EN, ENH, ENL, MASTER_EN			1.65 V	3 V to 5.5 V	0.67			0.08	1.1	V
				2.3 V		0.76			0.2	1.2	
				2.7 V		0.8			0.26	1.3	
				3 V		0.86			0.3	1.4	
V <sub>OH_S</sub>		V <sub>I</sub> = V <sub>IH</sub>		I <sub>OH</sub> = –100 μA	1.65 V to 3.6 V	V <sub>CC_S</sub> – 0.1			V <sub>CC_S</sub> – 0.2		V
				I <sub>OH</sub> = –2 mA	1.65 V	1.2			1.2		
				I <sub>OH</sub> = –4 mA	2.3 V	2			2		
				I <sub>OH</sub> = –6 mA	2.7 V	2.3			2.3		
				I <sub>OH</sub> = –12 mA	3 V	2.4			2.4		
V <sub>OL_S</sub>		V <sub>I</sub> = V <sub>IL</sub>		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V				0.1	0.2	V
				I <sub>OL</sub> = 2 mA	1.65 V				0.2	0.2	
				I <sub>OL</sub> = 4 mA	2.3 V				0.2	0.2	
				I <sub>OL</sub> = 6 mA	2.7 V				0.3	0.3	
				I <sub>OL</sub> = 12 mA	3 V				0.5	0.5	

(1) V<sub>CCI</sub> is the V<sub>CC</sub> associated with the input port.(2) V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.

### Electrical Characteristics<sup>(1)(2)</sup> (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V <sub>CC_S</sub>	V <sub>CC_CF</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		UNIT			
					MIN	TYP	MAX	MIN	MAX				
V <sub>OH_CF</sub>	V <sub>I</sub> = V <sub>IH</sub>	I <sub>OH</sub> = –100 μA	1.65 V to 3.6 V	3 V to 5.5 V	V <sub>CC_CF</sub> – 0.1			V <sub>CC_CF</sub> – 0.2		V			
		I <sub>OH</sub> = 12 mA		3 V							2.4	2.4	
		I <sub>OH</sub> = 16 mA		5.5 V							3.8	3.8	
V <sub>OL_CF</sub>	V <sub>I</sub> = V <sub>IL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	3 V to 5.5 V						V			
		I <sub>OL</sub> = 12 mA		3 V								0.5	0.5
		I <sub>OL</sub> = 16 mA		5.5 V								0.5	0.5
I <sub>I</sub>	Inputs without pullup resistor	V <sub>I</sub> = GND to V <sub>CC1</sub> <sup>(3)</sup>	1.65 V to 3.6 V	3.6 V to 5.5 V						μA			
	Inputs with pullup resistor	V <sub>I</sub> = V <sub>CC1</sub> <sup>(3)</sup> V <sub>I</sub> = 0 V		3 V to 5.5 V								±0.5	±1
I <sub>off</sub>	S port	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V	0 V	0 to 5.5 V						μA			
	CF port		0 to 3.6 V	0 V		±0.5	±1						
I <sub>OZ</sub> <sup>(4)</sup>	S or CF output ports	V <sub>O</sub> = V <sub>CCO</sub> or GND, V <sub>I</sub> = V <sub>CC1</sub> or GND	3.6 V	5.5 V						μA			
	CF outputs	MASTER_EN = V <sub>IH</sub> MASTER_EN = don't care		0 V		±0.5	±1						
I <sub>CC_S</sub>	Inputs (SD15–SD00, SA10–SA00, SCE1, SCE2, SIORD, SIOWR, SOE, SREG, SWE)	V <sub>I</sub> = V <sub>CC_S</sub> or GND	1.65 V to 3.6 V	3.6 V to 5.5 V			1.5		3	μA			
	Control inputs (ENL, ENH, BUF_EN)	ENL = ENH = BUF_EN = V <sub>CC_S</sub> One of ENL, ENH, BUF_EN = GND, Others = V <sub>CC_S</sub>						1.5			3		
								36		36			

(1) V<sub>CC1</sub> is the V<sub>CC</sub> associated with the input port.

(2) V<sub>CCO</sub> is the V<sub>CC</sub> associated with the output port.

(3) V<sub>CC1</sub> = V<sub>CC\_S</sub> for DIR( $\bar{S}$ /CF), ENL, ENH, SD15–SD00, SA10–SA00, MASTER\_EN, SRESET, SCE1, SCE2, SIORD, SIOWR, SOE, SREG, SWE, BUF\_EN

V<sub>CC1</sub> = V<sub>CC\_CF</sub> for D15–D00, BVD1, BVD2, INPACK, READY, WAIT, WP

(4) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

**Electrical Characteristics (continued)**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V <sub>CC_S</sub>	V <sub>CC_CF</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		UNIT
						MIN	TYP	MAX	MIN	MAX	
I <sub>CC_CF</sub>	Input (D15–D00)	V <sub>I</sub> = V <sub>CC_CF</sub> or GND	I <sub>O</sub> = 0, DIR( $\overline{S}/CF$ ) = GND, BVD1, BVD2, $\overline{INPACK}$ , READY, $\overline{WAIT}$ , WP = V <sub>CC_CF</sub>	1.65 V to 3.6 V	3 V to 5.5 V			1.5		3	μA
	Inputs (BVD1, BVD2, $\overline{INPACK}$ , READY, $\overline{WAIT}$ , WP)	BVD1 = BVD2 = $\overline{INPACK}$ = V <sub>CC_CF</sub> , READY, $\overline{WAIT}$ = V <sub>CC_CF</sub> , WP = V <sub>CC_CF</sub>	I <sub>O</sub> = 0, DIR( $\overline{S}/CF$ ) = GND, D15–D00 = V <sub>CC_CF</sub> or GND					1.5		3	
		One of BVD1, BVD2, $\overline{INPACK}$ , READY, $\overline{WAIT}$ , WP = GND, All others = V <sub>CC_CF</sub>	I <sub>O</sub> = 0, DIR( $\overline{S}/CF$ ) = GND, D15–D00 = V <sub>CC_CF</sub> or GND					60		60	
R <sub>INT</sub>				1.65 V to 3.6 V	3 V to 5.5 V			150	300	300	kΩ
C <sub>I</sub>	Control inputs	V <sub>I</sub> = 3.3 V or GND		3.3 V	3.3 V			3			pF
	S <sub>Axx</sub> , $\overline{SOE}$ , $\overline{SCE1}$ , $\overline{SCE2}$ , $\overline{SIORD}$ , $\overline{SIOWR}$ , $\overline{SREG}$ , $\overline{SWE}$							3			
	A <sub>xx</sub> , BVD1, BVD2, READY, $\overline{INPACK}$ , $\overline{WAIT}$ , WP							9			
C <sub>IO</sub>	S I/O ports	V <sub>O</sub> = 3.3 V or GND		3.3 V	3.3 V			7			pF
	CF I/O ports							12			

### Switching Characteristics

over recommended operating free-air temperature range ( $\overline{CD1}$ ,  $\overline{CD2}$ ) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC\_SD}$	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C to } 85^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{pd}$	$\overline{CD1}$ or $\overline{CD2}$	$\overline{SCD}$	$1.8\text{ V} \pm 0.15\text{ V}$	3.1	7.1	13.5	1.8	15.5	ns
			$2.5\text{ V} \pm 0.2\text{ V}$	2.7	4.6	7.1	1.6	9.1	
			$2.7\text{ V}$	2.4	4	5.7	1.6	9.1	
			$3.3\text{ V} \pm 0.3\text{ V}$	2	3.4	5.1	1.2	6.8	
			$5\text{ V} \pm 0.5\text{ V}$	1.7	2.6	3.6	1	5.5	

### Switching Characteristics

over recommended operating free-air temperature range ( $\overline{BVD1}$ ,  $\overline{BVD2}$ ,  $\overline{INPACK}$ ,  $\overline{READY}$ ,  $\overline{WAIT}$ ,  $\overline{WP}$ ) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	$V_{CC\_S}$	$V_{CC\_CF}$	$T_A = 25^\circ\text{C}$			$-40^\circ\text{C to } 85^\circ\text{C}$		UNIT	
						MIN	TYP	MAX	MIN	MAX		
$t_{pd}$	CF input	S output	$\overline{MASTER\_EN} = \overline{BUF\_EN} = V_{IL}$	$1.8\text{ V} \pm 0.15\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	3.1	6	10.2	2.4	12.9	ns	
					$5\text{ V} \pm 0.5\text{ V}$	2.9	5.6	9.6	2.2	13.9		
					$2.5\text{ V} \pm 0.2\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	2.7	4.6	6.5	1.9		10
						$5\text{ V} \pm 0.5\text{ V}$	2.5	4.2	5.8	1.7		8.6
					$3.3\text{ V} \pm 0.3\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	2.5	4	5.6	1.6		8.8
						$5\text{ V} \pm 0.5\text{ V}$	2.3	3.6	4.9	1.5		7
$t_{en}$	$\overline{MASTER\_EN}$	S output	$\overline{BUF\_EN} = V_{IL}$	$1.8\text{ V} \pm 0.15\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	11.1	18.9	30.7	9.2	35.5	ns	
					$5\text{ V} \pm 0.5\text{ V}$	11.1	19.3	30.9	8	35.6		
					$2.5\text{ V} \pm 0.2\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	9.9	12.9	17.4	6.9		22.6
						$5\text{ V} \pm 0.5\text{ V}$	9.9	13.1	17.4	7		22.6
					$3.3\text{ V} \pm 0.3\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	9.5	11.2	13.4	6.3		18.3
						$5\text{ V} \pm 0.5\text{ V}$	9.5	11.3	13.5	6.3		18.2
$t_{dis}$	$\overline{MASTER\_EN}$	S output	$\overline{BUF\_EN} = V_{IL}$	$1.8\text{ V} \pm 0.15\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	6.8	13.7	23.9	6	25.1	ns	
					$5\text{ V} \pm 0.5\text{ V}$	6.1	13.4	22	5.4	23.3		
					$2.5\text{ V} \pm 0.2\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	4.9	8.6	13.3	4		14.5
						$5\text{ V} \pm 0.5\text{ V}$	4.6	8.5	13.6	3.9		14.5
					$3.3\text{ V} \pm 0.3\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	5	8.1	12.2	4.2		13.2
						$5\text{ V} \pm 0.5\text{ V}$	4.5	8	12.2	3.6		18.2
$t_{en}$	$\overline{BUF\_EN}$	S output	$\overline{MASTER\_EN} = V_{IL}$	$1.8\text{ V} \pm 0.15\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	8.7	17.7	33.2	7.6	35.5	ns	
					$5\text{ V} \pm 0.5\text{ V}$	10.7	18.3	29.3	8.7	35.6		
					$2.5\text{ V} \pm 0.2\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	9.6	12.4	16.6	6.6		22.6
						$5\text{ V} \pm 0.5\text{ V}$	9.6	12.6	16.7	6.6		22.6
					$3.3\text{ V} \pm 0.3\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	9.2	10.9	13	6.1		18.3
						$5\text{ V} \pm 0.5\text{ V}$	9.2	10.9	13	6.1		18.2
$t_{dis}$	$\overline{BUF\_EN}$	S output	$\overline{MASTER\_EN} = V_{IL}$	$1.8\text{ V} \pm 0.15\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	6.9	12.9	22.3	5.9	24.2	ns	
					$5\text{ V} \pm 0.5\text{ V}$	5.4	12.4	20.5	4.8	22.8		
					$2.5\text{ V} \pm 0.2\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	4.4	8	12.7	3.6		14.5
						$5\text{ V} \pm 0.5\text{ V}$	4.2	7.9	12.8	3.6		14.2
					$3.3\text{ V} \pm 0.3\text{ V}$	$3.3\text{ V} \pm 0.3\text{ V}$	4.6	7.7	11.7	3.8		12.3
						$5\text{ V} \pm 0.5\text{ V}$	4.1	7.6	11.7	3.3		12.4

## Switching Characteristics

over recommended operating free-air temperature range (data bus I/Os) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V <sub>CC_S</sub>	V <sub>CC_CF</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		UNIT
						MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	D	SD	$\overline{\text{MASTER\_EN}} =$ $\overline{\text{ENL}} = \overline{\text{ENH}} = V_{\text{IL}}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	4.2	7.2	11.8	3	13.7	ns
					5 V ± 0.5 V	3.7	6.4	10.7	2.7	13.9	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	3.8	5.7	8	2.4	10	
					5 V ± 0.5 V	3.3	4.9	6.8	2.1	12.4	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	3.5	5.1	6.9	2.2	8.8	
					5 V ± 0.5 V	3	4.3	5.7	1.8	7	
	SD	D		1.8 V ± 0.15 V	3.3 V ± 0.3 V	3.4	5.7	9.8	2.6	11.1	
					5 V ± 0.5 V	3.1	5.4	9.6	2.4	9.6	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	2.8	4.3	6.2	1.9	8.2	
					5 V ± 0.5 V	2.6	3.8	5.4	1.7	7	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	2.5	3.7	5.2	1.5	7.2	
					5 V ± 0.5 V	2.2	3.3	4.5	1.4	6	
t <sub>en</sub>	$\overline{\text{MASTER\_EN}}$	D	$\overline{\text{ENL}} = \overline{\text{ENH}} = V_{\text{IL}}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	13.7	18.2	24.4	9.4	27.9	ns
					5.5 V ± 0.5 V	13.7	17.9	29.9	8	31	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	12.3	15.1	18.8	7.9	23	
					5.5 V ± 0.5 V	12.3	14.8	17.6	8	21.8	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	11.6	14	17.1	7.3	21.4	
					5.5 V ± 0.5 V	11.6	13.7	15.9	7.4	20.3	
	SD	D		1.8 V ± 0.15 V	3.3 V ± 0.3 V	11.6	19.6	31.8	9.4	36.3	
					5.5 V ± 0.5 V	11.7	20.1	32	9.5	36.2	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	10.3	13.4	18	7.2	22.6	
					5.5 V ± 0.5 V	10.3	13.6	18.1	7.1	22.6	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	9.8	11.6	14	6.4	18.3	
					5.5 V ± 0.5 V	9.8	11.7	14	6.4	18.2	
t <sub>dis</sub>	$\overline{\text{MASTER\_EN}}$	D	$\overline{\text{ENL}} = \overline{\text{ENH}} = V_{\text{IL}}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	8.6	12.8	18.1	7.3	20.2	ns
					5.5 V ± 0.5 V	7.6	11.5	16.4	6.3	17.8	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	7.8	10.8	14.7	6.4	16.4	
					5.5 V ± 0.5 V	6.7	9.4	12.6	5.4	13.8	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	7.2	9.9	13.4	5.9	15	
					5.5 V ± 0.5 V	6.1	8.6	11.4	4.8	12.5	
	SD	D		1.8 V ± 0.15 V	3.3 V ± 0.3 V	6.9	12.9	21.7	6	24.2	
					5.5 V ± 0.5 V	6.1	12.6	20.8	5.3	22.8	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	4.9	7.9	11.8	4.1	14.5	
					5.5 V ± 0.5 V	4.7	7.8	11.7	3.9	14.2	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	5	7.1	9.8	4	12	
					5.5 V ± 0.5 V	4.7	7	9.8	3.8	18.2	

### Switching Characteristics (continued)

over recommended operating free-air temperature range (data bus I/Os) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V <sub>CC_S</sub>	V <sub>CC_CF</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		UNIT
						MIN	TYP	MAX	MIN	MAX	
t <sub>en</sub>	ENL or ENH	D	MASTER_EN = V <sub>IL</sub>	1.8 V ± 0.15 V	3.3 V ± 0.3 V	9.4	17.6	23.4	8.3	27.2	ns
					5.5 V ± 0.5 V	13.5	17.4	22.6	7.7	27.8	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	12.3	15	18.5	7.9	22.8	
					5.5 V ± 0.5 V	12.3	14.7	17.4	8	21.6	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	11.7	14.1	17	7.3	21.4	
					5.5 V ± 0.5 V	11.6	13.7	16	7.4	20.3	
	SD	1.8 V ± 0.15 V		3.3 V ± 0.3 V	9.5	18.7	30.5	9.1	35.5		
				5.5 V ± 0.5 V	9.6	19.1	30.5	9.1	35.6		
		2.5 V ± 0.2 V		3.3 V ± 0.3 V	10	13	17.4	6.8	22.6		
				5.5 V ± 0.5 V	10	13.2	17.4	6.8	22.6		
		3.3 V ± 0.3 V		3.3 V ± 0.3 V	9.6	11.3	13.6	6.2	18.3		
				5.5 V ± 0.5 V	9.6	11.4	13.6	6.3	18.2		
t <sub>dis</sub>	ENL or ENH	D	MASTER_EN = V <sub>IL</sub>	1.8 V ± 0.15 V	3.3 V ± 0.3 V	8.5	12.1	16.8	7.2	20.2	ns
					5.5 V ± 0.5 V	7.7	10.8	15	6.3	16.6	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	7.6	10.4	13.8	6.2	16.4	
					5.5 V ± 0.5 V	6.9	9.1	11.9	5.4	13.1	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	7.3	9.7	12.9	5.9	15	
					5.5 V ± 0.5 V	6.5	8.4	11	5.2	12	
	SD	1.8 V ± 0.15 V		3.3 V ± 0.3 V	6.5	12	20	5.7	24.2		
				5.5 V ± 0.5 V	5.7	11.8	19	5	22.8		
		2.5 V ± 0.2 V		3.3 V ± 0.3 V	4.6	7.4	11.1	3.8	14.5		
				5.5 V ± 0.5 V	4.4	7.3	11.1	3.7	14.2		
		3.3 V ± 0.3 V		3.3 V ± 0.3 V	4.9	6.8	9.3	4	12		
				5.5 V ± 0.5 V	4.3	6.7	9.2	3.5	18.2		

### Switching Characteristics

over recommended operating free-air temperature range (SA10–SA00, SCE1, SCE2, SIORD, SIOWR, SOE, SREG, SWE)  
(see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V <sub>CC_S</sub>	V <sub>CC_CF</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		UNIT
						MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	S input	CF output (control)	$\overline{\text{MASTER\_EN}} = \overline{\text{BUF\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	3.4	6.1	9.8	2.5	10.4	ns
					5 V ± 0.5 V	3	5.8	9.7	2.4	10.2	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	2.6	4.5	6.7	1.8	8.4	
		5 V ± 0.5 V			2.4	4.1	6	1.7	6.8		
		3.3 V ± 0.3 V		3.3 V ± 0.3 V	2.2	3.9	5.8	1.4	7		
				5 V ± 0.5 V	2	3.5	5	1.3	5.8		
	CF output (A pins)	$\overline{\text{MASTER\_EN}} = \overline{\text{BUF\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	3.4	5.7	8.7	2.8	10.3		
				5 V ± 0.5 V	3.3	5.4	8.2	2.8	9.7		
			2.5 V ± 0.2 V	3.3 V ± 0.3 V	2.9	4.3	6.2	1.9	8.4		
				5 V ± 0.5 V	2.7	3.9	5.4	1.9	6.8		
			3.3 V ± 0.3 V	3.3 V ± 0.3 V	2.6	3.7	5.2	1.7	7		
				5 V ± 0.5 V	2.3	3.3	4.4	1.5	5.8		
t <sub>en</sub>	$\overline{\text{MASTER\_EN}}$	CF output (control)	$\overline{\text{BUF\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	10.8	17.9	24.8	7.9	29.7	ns
					5 V ± 0.5 V	10.8	17.5	26.2	8.1	30.2	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	9.4	14.2	19.4	6.4	23.3	
					5 V ± 0.5 V	9.4	14.1	19.3	6.6	23.1	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	8.7	13.1	17.8	5.8	21.4	
					5 V ± 0.5 V	8.7	13	17.5	6	21.2	
t <sub>dis</sub>	$\overline{\text{MASTER\_EN}}$	CF output (control)	$\overline{\text{BUF\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	7.3	13.8	22.5	6.2	25.8	ns
					5 V ± 0.5 V	6.8	12.1	19.7	5.9	26.3	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	6.1	11.8	19.2	4.9	20.2	
					5 V ± 0.5 V	5.9	10	16.3	4.6	19.8	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	5.6	11	18.3	4.6	19.1	
					5 V ± 0.5 V	5.4	9.2	15.5	3.9	18	
t <sub>en</sub>	$\overline{\text{BUF\_EN}}$	CF output (A pins)	$\overline{\text{MASTER\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	12.9	17.5	23.7	7.7	29.7	ns
					5 V ± 0.5 V	13.3	17.8	24.4	9.4	30.2	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	11.7	14.4	17.9	7.5	23.3	
					5 V ± 0.5 V	11.8	14.3	17.1	7.7	23.1	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	11	13.3	16.2	6.9	21.4	
					5 V ± 0.5 V	11.1	13.2	15.3	6.5	21.2	
t <sub>dis</sub>	$\overline{\text{BUF\_EN}}$	CF output (A pins)	$\overline{\text{MASTER\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	8.9	13.6	19.7	7.5	25.8	ns
					5 V ± 0.5 V	7.6	11.8	17.1	6.6	26.3	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	8	11.6	16	6.6	20.1	
					5 V ± 0.5 V	6.7	9.7	13.2	5	19.8	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	7.7	10.6	14.7	6	18.2	
					5 V ± 0.5 V	6.1	8.9	11.9	4.9	18	
t <sub>en</sub>	$\overline{\text{BUF\_EN}}$	CF output (A pins)	$\overline{\text{MASTER\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	12.3	16.4	21.9	7.7	27.2	ns
					5 V ± 0.5 V	12.6	16.7	22.6	8.6	29.1	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	11.2	13.8	17	7.1	21.7	
					5 V ± 0.5 V	11.4	13.7	16.3	7.3	21.5	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	10.7	12.9	15.6	6.7	19.5	
					5 V ± 0.5 V	10.8	12.8	14.8	6.5	19.6	

### Switching Characteristics (continued)

over recommended operating free-air temperature range (SA10–SA00, SCE1, SCE2, SIORD, SIOWR, SOE, SREG, SWE)  
(see Figure 1)

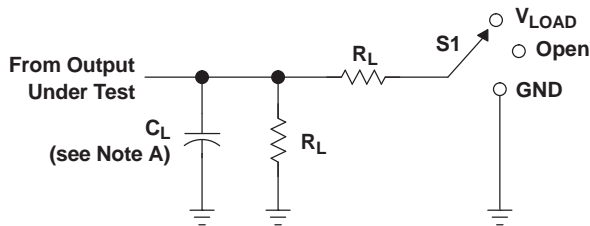
PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	V <sub>CC_S</sub>	V <sub>CC_CF</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C		UNIT
						MIN	TYP	MAX	MIN	MAX	
t <sub>dis</sub>	$\overline{\text{BUF\_EN}}$	CF output (A pins)	$\overline{\text{MASTER\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	8.4	13.9	21.2	7.2	23.2	ns
					5 V ± 0.5 V	7.6	12.3	18.5	6.6	23.7	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	7.7	12.3	18.2	6.4	19.8	
					5 V ± 0.5 V	6.7	10.6	15.3	5	18.4	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	7.2	11.5	16.4	5.9	18	
					5 V ± 0.5 V	6.4	10	14.3	4.9	17	
t <sub>en</sub>	$\overline{\text{BUF\_EN}}$	CF output	$\overline{\text{MASTER\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	12.5	16.6	22.3	8.7	27.2	ns
					5 V ± 0.5 V	12.8	17	23.1	8.8	29.1	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	11.4	14.1	17.5	7.3	21.7	
					5 V ± 0.5 V	11.6	14	16.9	7.4	21.5	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	10.9	13.2	16	6.8	20	
					5 V ± 0.5 V	11	13.1	15.3	6.5	19.6	
t <sub>dis</sub>	$\overline{\text{BUF\_EN}}$	CF output	$\overline{\text{MASTER\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	8.6	13.9	21.5	7.4	23.2	ns
					5 V ± 0.5 V	7.7	12.1	19.8	6.6	23.7	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	7.9	12.3	18.5	6.5	19.8	
					5 V ± 0.5 V	6.6	10.4	17.1	5	18.4	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	7.4	11.7	17.5	6.1	18.9	
					5 V ± 0.5 V	6.1	9.7	16.2	4.9	17	
t <sub>en</sub>	$\overline{\text{MASTER\_EN}}$	DIR_OUT	$\overline{\text{BUF\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	6.1	14.2	29.6	4.9	32.8	ns
					5 V ± 0.5 V	6	14.2	30	4.9	33.2	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	4.8	8.8	15.4	3.4	19.3	
					5 V ± 0.5 V	4.8	8.8	15.5	3.4	19.3	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	4.2	6.9	11.1	2.7	14.4	
					5 V ± 0.5 V	4.2	6.9	11.1	2.6	14.4	
t <sub>dis</sub>	$\overline{\text{MASTER\_EN}}$	DIR_OUT	$\overline{\text{BUF\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	5.4	10	16.6	4.2	32.6	ns
					5 V ± 0.5 V	5.4	9.9	16.1	4.8	32.6	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	3.9	6.5	10.5	1.5	19.3	
					5 V ± 0.5 V	3.9	6.6	10.4	1.7	19.3	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	4.4	6.7	10.3	1.4	14.4	
					5 V ± 0.5 V	4.3	6.7	10.1	1.5	14.4	
t <sub>pd</sub>	SIORD or SOE	DIR_OUT	$\overline{\text{BUF\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	5	9.3	15.7	4	17.9	ns
					5 V ± 0.5 V	5	9.3	15.7	4	17.9	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	3.9	6	8.5	2.8	11	
					5 V ± 0.5 V	3.9	6	8.5	2.8	11	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	3.3	4.7	6.2	2.2	8.2	
					5 V ± 0.5 V	3.3	4.7	6.2	2.2	8.2	
t <sub>pd</sub>	$\overline{\text{BUF\_EN}}$	DIR_OUT	$\overline{\text{BUF\_EN}} = V_{IL}$	1.8 V ± 0.15 V	3.3 V ± 0.3 V	8.9	19.5	35.9	7.1	39.2	ns
					5 V ± 0.5 V	8.9	19.5	35.8	7	39.3	
				2.5 V ± 0.2 V	3.3 V ± 0.3 V	6.8	11.9	19.1	5	22.8	
					5 V ± 0.5 V	6.8	11.9	19.2	4.9	22.8	
				3.3 V ± 0.3 V	3.3 V ± 0.3 V	5.8	9	13.3	4	15.8	
					5 V ± 0.5 V	5.8	9	13.3	3.9	15.9	

### Operating Characteristics

 $V_{CCS}$  and  $V_{CC\_CF} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ 

PARAMETER			TEST CONDITIONS	TYP	UNIT
$C_{pds}$	Power dissipation capacitance per transceiver	System-port input, CF-port output	Outputs enabled	$C_L = 0$ , $f = 10\text{ MHz}$	pF
			Outputs disabled		
	CF-port input, system-port output	Outputs enabled			
		Outputs disabled			
$C_{pdCF}$	Power dissipation capacitance per transceiver	System-port input, CF-port output	Outputs enabled	$C_L = 0$ , $f = 10\text{ MHz}$	pF
			Outputs disabled		
	CF-port input, system-port output	Outputs enabled			
		Outputs disabled			

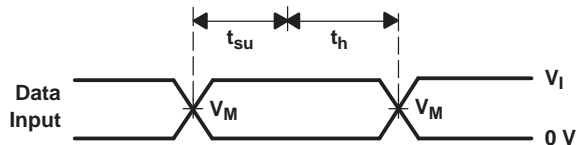
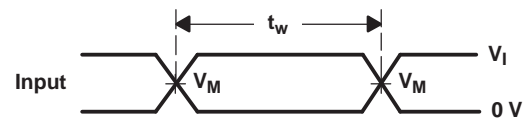
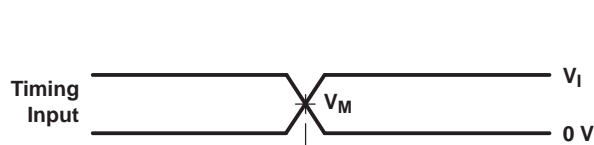
PARAMETER MEASUREMENT INFORMATION



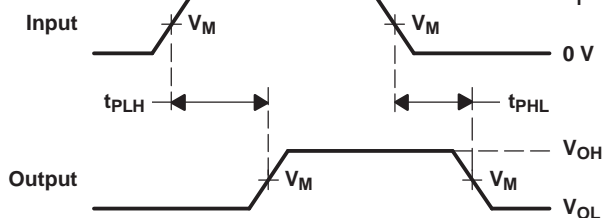
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PHZ}$	GND

LOAD CIRCUIT

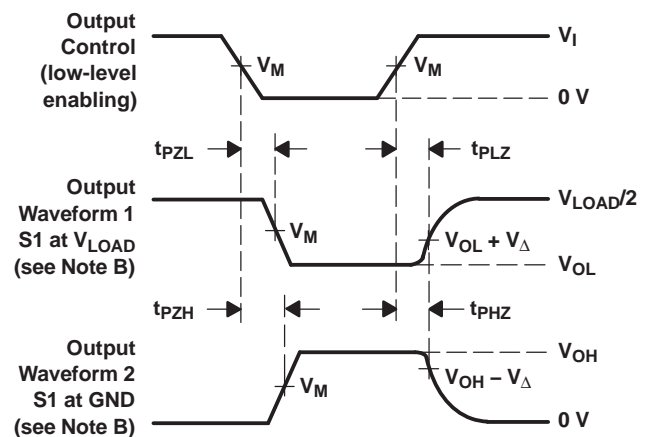
$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8 V \pm 0.15 V$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 k $\Omega$	0.15 V
$2.5 \pm 0.2 V$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	2 k $\Omega$	0.15 V
2.7 V	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	15 pF	2 k $\Omega$	0.3 V
$3.3 V \pm 0.3 V$	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	15 pF	2 k $\Omega$	0.3 V
$5.5 V \pm 0.5 V$	2.7 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	15 pF	2 k $\Omega$	0.5 V



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_0 = 50 \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CF4320HGKFR	NRND	LFBGA	GKF	114	1000	TBD	SNPB	Level-3-220C-168 HR
CF4320HZKFR	ACTIVE	LFBGA	ZKF	114	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

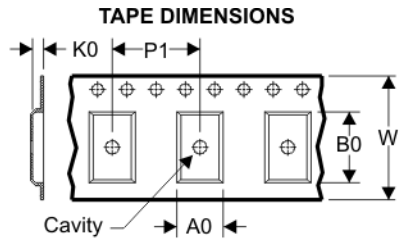
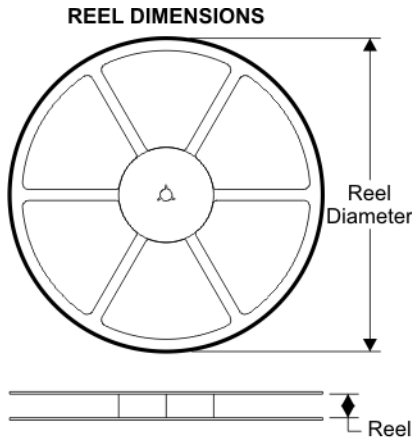
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

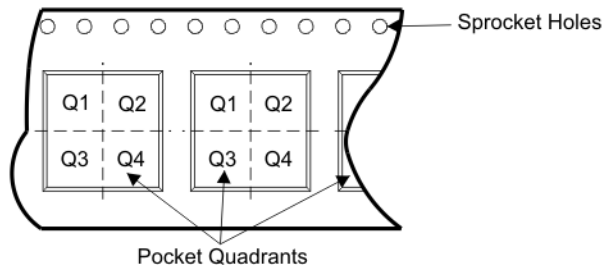
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL BOX INFORMATION**



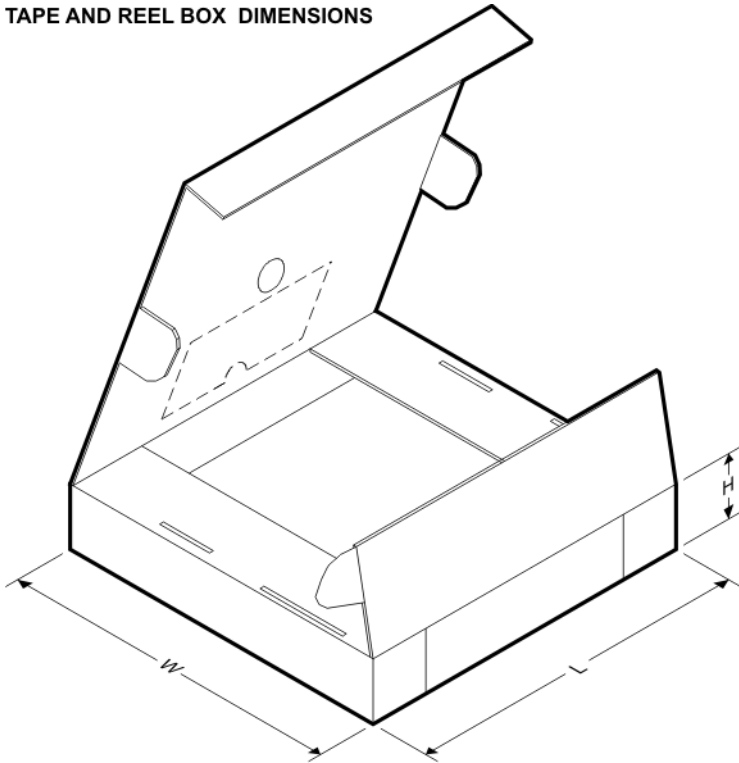
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CF4320HGKFR	GKF	114	SITE 32	330	24	5.8	16.3	1.8	8	24	Q1
CF4320HZKFR	ZKF	114	SITE 32	330	24	5.8	16.3	1.8	8	24	Q1

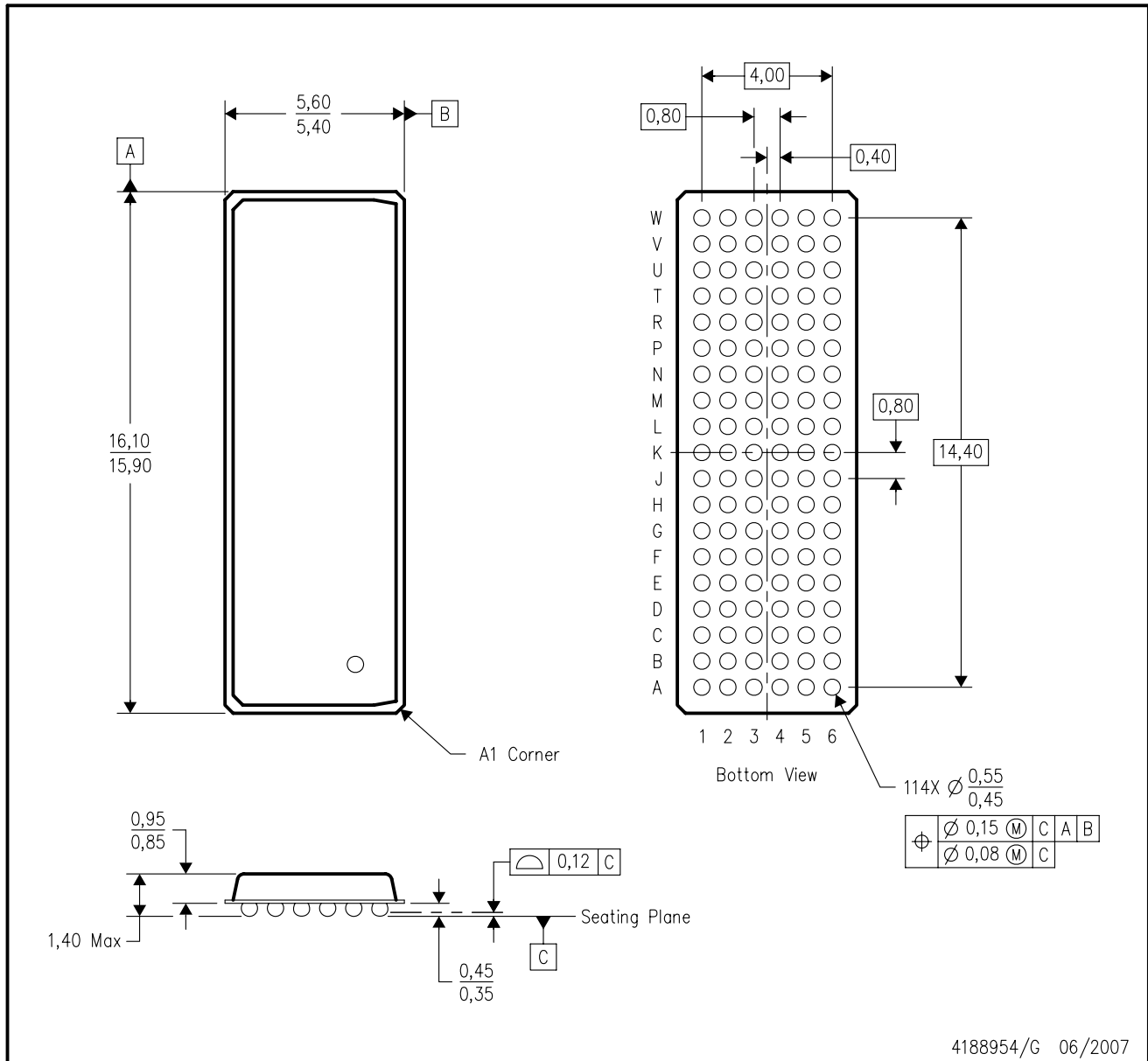
**TAPE AND REEL BOX DIMENSIONS**



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
CF4320HGKFR	GKF	114	SITE 32	346.0	346.0	41.0
CF4320HZKFR	ZKF	114	SITE 32	346.0	346.0	41.0

GKF (R-PBGA-N114)

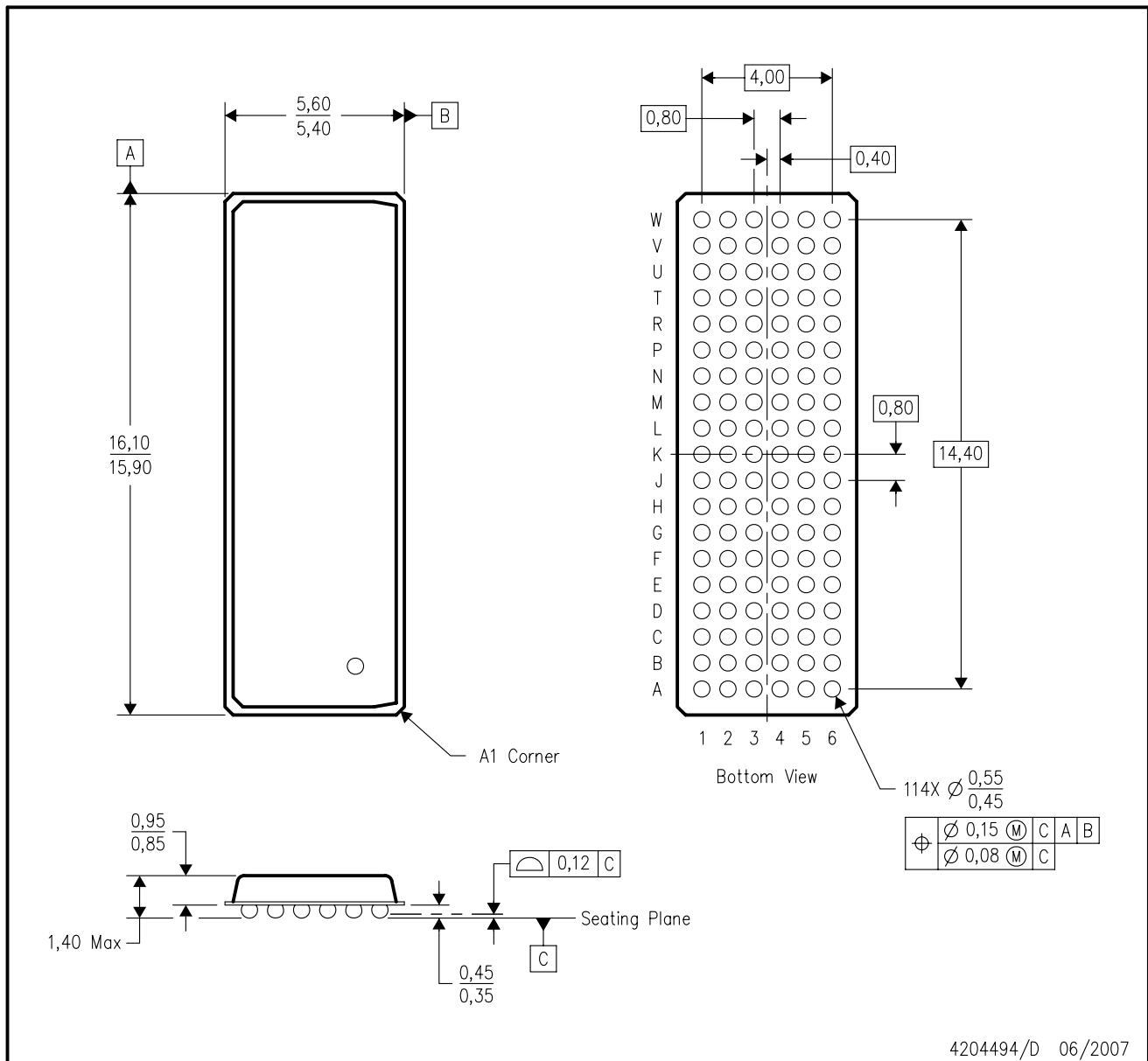
PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation DC.
  - D. This package is tin-lead (SnPb). Refer to the 114 ZKF package (drawing 4204494) for lead-free.

ZKF (R-PBGA-N114)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation DC.
  - D. This package is lead-free. Refer to the 114 GKF package (drawing 4188954) for tin-lead (SnPb).

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<b>Products</b>		<b>Applications</b>	
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>	Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Digital Control	<a href="http://www.ti.com/digitalcontrol">www.ti.com/digitalcontrol</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Military	<a href="http://www.ti.com/military">www.ti.com/military</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Optical Networking	<a href="http://www.ti.com/opticalnetwork">www.ti.com/opticalnetwork</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>	Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
Low Power Wireless	<a href="http://www.ti.com/lpw">www.ti.com/lpw</a>	Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
		Wireless	<a href="http://www.ti.com/wireless">www.ti.com/wireless</a>

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2007, Texas Instruments Incorporated